



Applicant:	Irwin Aberin et al.	Examiner:	Unknown
Serial No.:	10/588,927	Group Art Unit:	Unknown
Filed:	August 9, 2006	Docket No.:	I431.168.101/FIN 581 PCT/US
Title:	SEMICONDUCTOR PACKAGE WIT	H PERFORATED SUBSTRA	TE
Commissio P.O. Box 14	mendment ner for Patents 50 VA 22313-1450		
Sir:			
We are tran	smitting herewith the attached:		
✓ Inform✓ Form P	nittal Sheet containing Certificate of ation Disclosure Statement TO-1449 <u>1</u> pg(s). f <u>5</u> cited references	of Mailing under 37 C.F.R. <u>2</u> pg(s).	1.8
☐ The Co	ommissioner is authorized to charg	ge \$0.00 to Deposit Ac	count No. 500471 to cover the require
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Date of Deposit: 03/07/07	
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Patents, P.O. Box 1450, Alexandria, VA 22313-1450.	to: Mail stup Affenditient Commissioner for
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	Name: Paul P. Kempf
	, au. , , , , , , , , , , , , , , , , , , ,

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Irwin Aberin et al.

Examiner: Unassigned

Serial No.:

10/588,927

Group Art Unit: Unassigned

Filed:

August 9, 2006

Docket: I431.168.101/FIN 581 PCT/US

Title:

SEMICONDUCTOR PACKAGE WITH PERFORATED SUBSTRATE

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

In compliance with the duty of disclosure under 37 C.F.R. § 1.56, it is respectfully requested that this Information Disclosure Statement be entered and the documents listed on attached form 1449 be considered by the Examiner and made of record. Any required copies of patents, publications or other documents are enclosed for the Examiner's review. Pursuant to the provisions of M.P.E.P. 609, Applicant further requests a copy of the 1449 form, marked as being considered and initialed by the Examiner, be returned with the next Official Communication.

Since this Information Disclosure Statement is being submitted within three months of filing national application; or date of entry of national application; or before the mailing date of the first Office Action on the merits, a fee has not been enclosed. However, if such fee is required, the Patent Office is hereby authorized to charge Deposit Account No. 500471 for fees as set forth under 37 C.F.R. 1.17(p).

Information Disclosure Statement

Applicant: Irwin Aberin et al. Serial No.: 10/588,927 Filed: August 9, 2006

Docket No.: I431.168.101/FIN 581 PCT/US

Title: SEMICONDUCTOR PACKAGE WITH PERFORATED SUBSTRATE

Applicant respectfully requests consideration of these references during prosecution of the above-identified matter. The Examiner is invited to contact the Applicant's representative at the below-listed telephone number if there are any questions regarding this Communication or the tendered references.

Respectfully submitted,

Irwin Aberin et al.,

By their attorneys,

DICKE, BILLIG & CZAJA, PLLC Fifth Street Towers, Suite 2250 100 South Fifth Street Minneapolis, MN 55402

Telephone: (612) 767-2502 Facsimile: (612) 573-2005

Dated: 15

PPK:mlm

Paul P. Kempf

Reg. No. 39,727

<u>CERTIFICATE UNDER 37 C.F.R. 1.8</u>: The undersigned hereby certifies that this paper or papers, as described herein, are being deposited in the United States Postal Service, as first class mail, in an envelope address to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this day of March, 2007.

Name: Paul P. Kempf

FORM PTO-1449 Docket No.: I431.168.101 Serial No.: 10/588,927 Applicant: Irwin Aberin et al. Filing Date: August 9, 2006 Group Art:

U.S. PATENT DOCUMENTS

PADEM		- 1	T			
Examiner Initial	Document No.	Date	Name	Class	Sub Class	Filing Date If Appropriate
AA	6,014,318	01/11/2000	Takeda			
AB	6,054,755	04/25/2000	Takamichi et al.			
AC	6,285,086	09/04/2001	Sota et al.			
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AE	2002/0076858	06/20/2002	Dotta et al.			
AF						
AG						
АН						
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AJ				,		and a contract of the contract
AK						
AL						

FOREIGN PATENT DOCUMENTS

	Document No.	Date	Country	Class	Sub Class	Translated Yes No
AN	л JP03283453	12/13/1991	Japan			Yes (Abstract only)
Aì	KR2002016126	03/04/2002	Korea			Yes (Abstract only)
AC	KR2002064592	08/09/2002	Korea			Yes (Abstract only)

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

AR	Wong et al., "Advanced Moisture Diffusion Modeling Components and Technology Conference, 0-7803-74	g & Characterisation for Electronic Packaging", 2002 Electronic 30-4/02/\$17.00 ©2002 IEEE.
AS	Wong et al., "The Mechanics and Impact of Hygrosco Electronic Components and Technology Conference,	opic Swelling of Polymeric Materials in Electronic Packaging", 0-7803-5911-9/00/\$10.00 (c)2000 IEEE
AT		
EXAMINER:		DATE CONSIDERED:

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.